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## AMENDMENTS TO THE SPECIFICATION

Please replace the paragraph bridging pages 124 and 125 with the following amended paragraph:

As the metal particles, there can be used copper, gold, silver, aluminum, nickel, titanium, chromium, tin/lead, palladium, platinum and the like. The particle diameter of those metal particles is preferably 0.1 to 50  $\mu$ m. This is because [[,]] the surface of copper is oxidized to worsen wettability against the resin when the diameter is less than 0.1  $\mu$ m, while the printing efficiency becomes worse when the diameter is over 50  $\mu$ m. The addition amount of the metal particles is preferably 30 to 90 wt.%. This is because the adhesion of cover plating becomes worse when the amount is less than 30 wt.%, while the printing efficiency becomes worse when the amount is over 90 wt.%.